# **Oral Presentations**

Wednesday, May 16 (A)

	wednesday, May 10 (A)
10:00	Opening Remarks (10:00am-10:10am) Conference Hall (7 <sup>th</sup> Floor)  Miyamoto Isamu
	Session 1A: Overview Conference Hall (7 <sup>th</sup> Floor)
10:10	Chair: Sugioka Koji, RIKEN (Institute of physical and Chemical research) (Japan)
	Laser microprocessing in data storage industry (Invited Paper), Chong Tow Chong, DSI (Singapore)
	<ul> <li>Femtosecond pulses for medicine and production technology - Overview of a German national project (Invited Paper), Dausinger Friedrich, University of Stuttgart (Germany) [A086]</li> <li>Review on recent progress of laser precision microfabrication in China (Invited Paper), Cheng Zhao Gu, Xu Guoliang, Zhao Quanzhong, Chinese Academy of Sciences (China) [A068]</li> <li>History and future prospect of excimer lasers (Invited Paper), Basting Dirk, Lambda Physik (Germany) [A110]</li> </ul>
	<b>Lunch</b> (12:10pm-1:40pm)
13:40	Session 2A: Ultrafast Laser Processing(1) Conference Hall (7 <sup>th</sup> Floor) Chair: Mazur Eric, Harvard University (USA)
	Optimum energy absorption of a short-pulse laser in a doped dielectric slab, Ang LayKee, Los Alamos
	<ul> <li>Optimum energy absorption of a short-pulse laser in a doped dielectric stab, Ang Laykee, Los Alamos National Laboratory (USA) [A002]</li> <li>Sub-Picosecond ion emission from transparent dielectrics, Henyk M., Costache F., Reif J., Brandenburg University of Technology (Germany) [A055]</li> <li>Ultrafast laser ablation of dielectrics employing temporally shaped femtosecond pulses, Stoian R.,</li> </ul>
	Boyle M., Thoss A., Rosenfeld A., Korn G., Hertel I.V., Max-Born Institute; Ashkensai D., Laser und medizin Technologie GmbH (Germany), Cambell E.E.B., Goteborg University and Chalmers University of
	Technology (Sweden)  • Laser-induced expansion, melting and ablation mechanisms of organic materials (Invited Paper),  [A035]
	Masuhara Hiroshi, Osaka University (Japan) [A102]
	Coffee Break (3:10pm-3:30pm)
15:30	Session 3A: Ultrafast Laser Processing (2) Conference Hall (7 <sup>th</sup> Floor) Chair: Masuhara Hiroshi, Osaka University (Japan)
	• Micromachining and laser processing with ultrashort laser pulses (Invited Paper), Mazur Eric, Harvard University (USA) [A103]
	<ul> <li>Precision drilling of metals and ceramics with short and ultrashort pulsed solid-state lasers, Christian Föhl, Breitling D., Jasper K., Radtke J., Dausinger F., University of Stuttgart (Germany) [A087]</li> <li>Morphological characterization of various kinds of materials in femtosecond-laser micromachining, Kawahara Kousuke, Kurogi Yasunobu, Matsuo Naoyuki, Yokotani Atsushi, Kurosawa Kou, University of</li> </ul>
	Miyazaki; Sawada Hiroshi, NEC Machinery Corporation (Japan) [A062]
	• Ultra-short pulsed laser recrystallization of crystalline silicon, Cho Taeyouli, Hwang David J., Grigoropoulos Costas P., University of California (USA) [A079]
	Coffee Break (5:00pm-5:20pm)
17:20	Rump Session: (5:20pm – 7:20pm)Conference Hall (7 <sup>th</sup> Floor)  Chair: Dunsky Corey, Electro Scientific Industries (USA)  Hoving Willem, Philips Electronics Nederland B.V. (Netherlands)
	Present status and future prospects of laser precision microfabrication in Japan, Washio Kunihiko, NEC (Japan)
	Present status and future prospects of laser precision microfabrication about former USSR states, Veiko Vadim P., SPIFMO (Russia)
	Overview presentation of Europe's micromachining activities seems to be appropriate, Ostendorf
	Andreas, Laser Zentrum Hannover e.V. (Germany)
	Present status and future prospects of laser precision microfabrication on government supported
	<ul> <li>programs, Helvajian Henry, Aerospace Corp. (USA)</li> <li>Industrial LD application for materials processing – present status and future prospect, Bachmann</li> </ul>
	Friedrich, Rofin-Sinal Laser (Germany)  • LPM technology to be developed in future, Miyamoto Isamu, Osaka University (Japan)

# Wednesday, May 16 (B)

10:00	Opening Remarks (10:00am-10:10am) Conference Hall (7 <sup>th</sup> Floor)  Miyamoto Isamu
10:10	Session 1A: Overview Conference Hall (7 <sup>th</sup> Floor) Chair: Sugioka Koji, RIKEN (Institute of physical and Chemical research) (Japan)
	<ul> <li>Laser microprocessing in data storage industry (Invited Paper), Chong Tow Chong, DSI (Singapore)</li></ul>
	<b>Lunch</b> (12:00pm-1:40pm)
13:40	Session 2B: Systems and Optics (1) Training Room (6 <sup>th</sup> Floor) Chair: Gower Malcom C., Exitec (UK)
	• Novel ultrafast fiber laser systems and their applications (Invited paper), Endert Heinrich, IMRA (USA) [A108]
	<ul> <li>Femtosecond pulsed laser sub-micromachining system, Ngoi K.A., Venkatakrishnan K., Tan B., Nanyang Technological University (Singapore) [A032]</li> <li>High-reliable high-power 266-nm all-solid-state UV laser, Kojima Tetsuo, Konnno Sususmu, Fujikawa Shuichi, Seguchi Masaaki, Takenaka Yushi, Yasui Koji, Mitsubishi Electric Corporation (Japan) [A092]</li> <li>Recent developments in precision micromachining using pulsed UV DPSS lasers, Chang Andrew, Somerville Paul, Hannon Terry, Coherent Photonics Group (USA) [A097]</li> </ul>
	Coffee Break (3:10pm-3:30pm)
15:30	Session 3B: Systems and Optics (2) Training Room (6 <sup>th</sup> Floor) Chair: Jitsuno Takahisa, ILE Osaka University (Japan)
	<ul> <li>12 Watts of UV at 355nm, Dafydd Thomas, Spectra Physics Inc. (USA) [A143]</li> <li>300 W XeCl excimer laser for large area TFT laser annealing, Fechner Burkhard, Lambda Physik Japan Co., Ltd. (Japan), Fiebig Michael, Lambda Physik AG, Oesterlin Peter, MicroLas Lasersystem GmbH(Germany), Kobayashi Naoyuki, The Japan Steel Works (Japan) [A051]</li> <li>In-situ measurements of VUV optical material under F2 laser irradiation, Sumitani Akira, Itakura Yasuo, Yoshida Fumika, Kawasa Youichi, Komatsu Ltd.; Wakabayashi Osamu, Mizoguchi Hakaru Gigaphoton Inc. (Japan) [A095]</li> <li>What engineers should know about lasers, Witt Manfred, Zugo Technology Pte Ltd. (Singapore) [A019]</li> </ul>
	Coffee Break (4:50pm-5:20pm)
17:20	Rump Session: (5:20pm – 7:20pm)Conference Hall (7 <sup>th</sup> Floor)  Chair: Dunsky Corey, Electro Scientific Industries (USA)  Hoving Willem, Philips Electronics Nederland B.V. (Netherlands)  Present status and future prospects of laser precision microfabrication in Japan, Washio Kunihiko, NEC (Japan)
	Present status and future prospects of laser precision microfabrication about former USSR states,     Veiko Vadim P., SPIFMO (Russia)  Overview presentation of Europe's migromachining activities geometric be emprecised. October 1.
	Overview presentation of Europe's micromachining activities seems to be appropriate, Ostendorf Andreas, Laser Zentrum Hannover e.V. (Germany)  Present status and future presents of leave president in microfich richtien are consumered appropriate.
	Present status and future prospects of laser precision microfabrication on government supported programs, Helvajian Henry, Aerospace Corp. (USA)  La destrict I. D. and instance for materials are assistant property and future programs.
	Industrial LD application for materials processing – present status and future prospect, Bachmann Friedrich, Rofin-Sinal Laser (Germany)  LPM technology to be developed in future. Mixemote Jeany, Ocelea University (Jenes)
	LPM technology to be developed in future, Miyamoto Isamu, Osaka University (Japan)

# Thursday, May 17 (A)

9:00	<ul> <li>Session 4A: Optics Fabrication Conference Hall (7<sup>th</sup> Floor)         Chair: Gillner Arnold, Fraunhofer-Institut für Lasertechnik (Germany)     </li> <li>Laser shaping of diamond for IR diffractive optical elements (Invited Paper), Konov Vitali, Kokonenko Vitali, Pimenov Sergei, Prokhorov Alexander, General Physics Institute, Moscow, Pavelyev Vladimir, Soifer Victor, Institute of Image Processing Systems, Samara (Russia) [A071]</li> <li>Laser ablative shaping of microoptics for laser diode and optical fiber, Jitsuno Takahisa, Institute of Laser Engineering, Osaka University; Tokumura K., Nalux Co. Ltd.; Tamamura H., Sony/Tektronix Co. (Japan)</li></ul>
	Coffee Break (10:30am-10:50am)
10:50	Session 5A: Microfabrication and Microstructuring Conference Hall (7 <sup>th</sup> Floor) Chair: Helvajian Henry, The Aerospace Corporation (USA)
	<ul> <li>Laser micro-fabrications: from present to future applications (Invited Paper), Lim Gnian Cher, Gintic (Singapore)         <ul> <li>Generation of periodic microstructures with femtosecond laser pulses, Tönshoff H.K., Ostendorf A., Egbert A., Korte F., Bauer T., Laser Zentrum Hannover e.V. (Germany)</li></ul></li></ul>
	<b>Lunch</b> (12:20pm-1:30pm)
13:30	1:30pm-2:30pm: Poster Presentation
14:30	Session 6A: Advanced Microfabrication Technology Conference Hall (7 <sup>th</sup> Floor) Chair: Holmes Andrew, University of London (UK)
	<ul> <li>Laser processes for manufacturing micro devices in chemistry and biotechnology (Invited Paper), Gillner Arnold, Fraunhofer-Institute füer lasertechnik (Germany) [A109]</li> <li>Laser ablation patterning of dielectric layer stacks for 193nm mask fabrication, Ihlemann Jurgen, Rubahn Katharina, Laser-Laboratorium Gottingen; Thielsch Roland, Fraunhofer Institute (Germany) [A061]</li> <li>Precision machining of innovative materials using 157 nm excimer laser radiation, Ostendorf Andreas, Laserzentrum Hannover; Stamm Uwe, Lambda Physik AG (Germany) [A096]</li> <li>Characterization of fused silica ablation by F<sub>2</sub>-KrF excimer laser multiwavelength excitation process, Obata Kotaro, Sugioka Koji, Akane Toshimitsu, Midorikawa Katsumi, RIKEN (The institute of physical and chemical research), Aoki Naoko, Toyoda Koichi, Science University of Tokyo (Japan) [A084]</li> <li>Laser writing of nano-structure on silicon (100) surfaces with particle enhanced optical irradiation, Lu Y.F., Zhang L., Song W.D., Zheng Y.W., Luk'yanchuk B.S, National University of Singapore, Data Storage Institute (Singapore) [A005]</li> <li>GaN micro machining by short wavelength pulsed laser irradiation, Akane Toshimitsu, Sugioka Koji, Midorikawa Katsumi, RIKEN (The Institute of Physical and Chemical Research), Obata Kotaro, Aoki Naoko, Toyoda Koichi, Science University of Tokyo (Japan) [A089]</li> </ul>
17:00	Transport to Cruise (4:40pm-5:00pm)  Cruise Excursion (5:00pm-8:00pm)

### Thursday, May 17 (B)

9:00	Session 4B: Fundamental Aspects (1) Training Room (6 <sup>th</sup> Floor) Chairs: Liu DaMing, Data Storage Institute (Singapore)
9.00	<ul> <li>Particle on the surface: Basic physical problems related to laser cleaning (Invited Paper), Luk`yanchuk B.S., Zheng Y.W., Lu Y.F., DSI (Singapore) [A033]</li> <li>Microstructures formed on silicon wafer by CO<sub>2</sub> Laser irradiation, Wang Weijie, Lu Yong Feng, An Chenwu, Hong Minghui, DSI (Singapore) [A040]</li> <li>Dynamical observation of laser-induced damages made in inside of transparent materials, Ito Yoshiro, Kiyoku Satoshi, Ogura Tsutomu, Department of Mechanical Engineering, Nagaoka University of Technology; Mohri Naotake, Department of Precision Engineering, The University of Tokyo (Japan) [A081]</li> <li>Observation of temporary degeneration of material transmittance under strong laser irradiation, An C.W, Ler K.L, Yuan Y, Goh Y.W, Hong M.H and Lu Y.F, DSI (Singapore) [A043]</li> </ul>
	Coffee Break (10:30am-10:50am)
10:50	Session 5B: Fundamental Aspects(2) Training Room (6 <sup>th</sup> Floor)  Chairs: Veiko Vadim P., St. Petersburg Institute of fine Mechanics and Optics (Russia)
	<ul> <li>Fundamentals of particle adhesion and removal from surfaces (Invited Paper), Rajiv K. Singh, University of Florida (USA) [A128]</li> <li>Scattering of evaporated particles in ultrashort-pulse laser ablation, Ohmura Etsuji, Osaka University (Japan) [A111]</li> <li>The fundamental aspect of microscale laser bending, Xu XianFan, School of Mechanical Eng., Purdue University (USA) [A085]</li> <li>Laser induced rear ablation of metal thin films, Sano Tomokazu, Nakayama Takayuki, Yamada Hirokazu, Miyamoto Isamu, Osaka University (Japan) [A118]</li> </ul>
	<b>Lunch</b> (12:20pm-1:30pm)
13:30	1:30pm-2:30 pm: Poster Presentation
14:30	Session 6B: Pulsed Laser Deposition Training Room (6 <sup>th</sup> Floor) Chair: Okada Tatsuo, Kyushu University (Japan)
	<ul> <li>Pulsed-laser deposition of carbon and nitride materials (Invited Paper), Ren Zhong Min, Lu Y.F., Huang S.M., He Z.F., Hong M.H., Chong T.C., Data Storage Institute, National University of Singapore (Singapore)</li></ul>
	<ul> <li>Pulsed laser deposition of nanocrystalline ZnSe:N thin film, Xu Ning, Fudan University (China) [A028]</li> <li>Fabrication of Ce:YIG film with different composition by pulsed-laser deposition, Nakata Yoshiki, Tashiro Yuko, Okada Tatsuo, Maeda Mitsuo, Higuchi Sadao, Ueda Kiyotaka, Kyushu University (Japan) [A065]</li> </ul>
	Transport to Cruise (4:40pm-5:00pm)
17:00	Cruise Excursion (5:00pm-8:00pm)

#### Friday, May 18 (A)

Session 7A: Microsystems and Microelements --- Conference Hall (7th Floor) 9:00 Chair: Konov Vitali I, General Physics Institute, Moscow (Russia) Laser processes for MEMS manufacture (Invited paper), Holmes Andrew, Imperial College, University of London (UK) Laser beam adjustment of thin metal plates, Frank Meyer-Pittroff, University of Erlangen-Nuremberg (Germany) [A013] Laser micromachining of micropumps, Mai Tuan Anh, Gintic Institute of Manufacturing Technology [A058] (Singapore) Laser volumetric patterning for embedded interface processing in a photostructurable Glass/Ceramic material, Hansen W., Fuqua P., Helvajian H., The Aerospace Corporation (USA) [A123] Coffee Break (10:30am-10:50am) Session 8A: Industrial Applications (1) --- Conference Hall (7<sup>th</sup> Floor) 10:50 **Chair: Sepold Gerd,** University of Blemen (Germany) Ultra line-narrowed F<sub>2</sub> laser for microlithography (Invited Paper), Ariga Tatsuya, Watanabe Hidenori, Kumazaki Takahito, Kitatochi Naoki, Sasano Kotaro, Ueno Yoshifumi, Nishisaka Toshihiro, Nohdomi Ryoichi, Hotta Kazuaki, Mizoguchi Hakaru, Nakao Kiyoharu, Association of Super-Advanced Electronics Technologies (ASET) (Japan) High-resolution 157nm imaging for lithography and micromachining applications, Gower Malcolm, Cashmore Julian, Whitfield Mike, Grünewald Philipp, Exitech Ltd. (UK) [A074] Developments in laser welding of plastics using high power diode lasers, Hoult Tony, Apter Merrill, [A098] Chang Andrew, Coherent Photonics Group (USA) Polymer welding with lasers: chances and hurdles, Bachmann Friedrich, Rofin-Sinar Laser GmbH [A057] (Germany) Lunch (12:20pm-1:20pm) 13:20 1:20pm-2:20pm: Poster Presentation Session 9A: Industrial Applications (2) --- Conference Hall (7<sup>th</sup> Floor) 14:20 Chair: Washio Kunihiko, NEC Corporation (Japan) High-speed microvia formation with UV YAG lasers (Invited Paper), Dunsky Corey, Matsumoto Hisashi, Simenson Glenn, Electro Scientific Industries (USA) [A072] High accuracy laser mask repair technology using ps UV solid state laser (Invited Paper), Morishige Yukio, NEC (Japan) [A106] The study of BGA singulation with a pulsed Nd:YAG laser, Kwangyeol Baek, Kyoungcheol Lee, Cheon Lee, Inha university (Korea) [A036] A study of glass cutting by laser, Kang, Hyoung-Shik, Hong, Soon-Kug, Oh, Seok-Chang, Choi, Jong-Yoon, Song, Min-Gyu, LG Production Engineering Research Center (Korea) [A030] Coffee Break (4:00pm-4:20pm) Session 10A: Industrial Applications (3) --- Conference Hall (7<sup>th</sup> Floor) 16:20 Chair: Dausinger Friedrich, University of Stuttgart (Germany) Excimer laser crystallized poly-Si TFTs on plastic substrates (Invited Paper), Gosain Dharam Pal, Frontier Science Laboratories, Yokohama Research Centre, Sony Corporation (Japan) [A073] Precise laser-assisted 3D- microstructuring on metals and alloys (Invited Paper), G. Sepold, Univ. [A124] Blemen (Germany) Comparison of micro drilling strategies for ceramics using frequency convertible Nd:YAG and Excimer lasers, Tönshoff H.K., Ostendorf A., Körber K., Meyer K., Laser Zentrum Hannover e.V. [A076] (Germany) Laser adjustment, a novel technique to obtain fast, sub-micron accuracy in mass production, Willem Hoving, Philips Electronics Nederland B.V. (Netherlands) [A121] Closing Remarks (6:00pm-6:10pm) --- Conference Hall (7th Floor) 18:00 Lu YongFeng

# Friday, May 18 (B)

Filday, May 18 (D)
Session 7B: Laser Cleaning Workshop Training Room (6 <sup>th</sup> Floor) Chair: Fotakis C., FORTH-IESL (Greece)
<ul> <li>Physical principles of Steam Laser Cleaning (Invited Paper), Paul Leiderer, Konstanz University (Germany)         [A142]         This talk of Prof. P. Leiderer will replace the talk of Prof. A.C. Tam who had left us early this year.     </li> <li>The emergence of laser cleaning for hi-tech industrial applications (Invited Paper), Tam A.C., IBM Almaden research center (USA)         [A125]     </li> <li>Laser induced surface cleaning from diamond particles (Invited Paper), Konov V.I., RAS; Kononenko V.V., Lomonosov A.M., Mihalevich V.G., Pimenov S.M., Zhuk K.A., General Physics Institute Moscow (Russia)         [A138]     </li> <li>Wavelength dependence of laser cleaning for field emitter arrays (Invited Paper), Takai Mikio, Suzuki Naoki, Yavas Oguz, (Japan)         [A126]         Coffee Break (10:30am-10:40am)     </li> <li>Session 8B: Laser Cleaning Workshop Training Room (6<sup>th</sup> Floor)         Chairs: Takai M., (Japan)         Lu YongFeng, Data Storage Institute, National University of Singapore (Singapore)     </li> <li>Laser technology of artworks and antiquities: Fundamental aspects and prospects (Invited Paper),         Fotakis C., Georgiou S., Zafiropulos V., Heraklion, FORTH-IESL (Greece)         [A107]     </li> <li>Laser cleaning of silicon wafers – mechanisms and efficiencies (Invited Paper), Mosbacher M., Münzer HJ., Dobler V., Bertsch M., Dubbers O., Mühlberger T., Schrems G., Boneberg J., Bäuerle D., Solis J., Oltra R., Leiderer P., Runge B.U., (Germany); (Austria); (Spain); (France)         [A127]     </li> <li>Dry laser cleaning threshold fluence – How can it be measured accurately? (Invited Paper), Fernandes Alanna, Kane Deborah, Physics Department, Macquarie University (Australia)     </li> </ul>
• Liquid-assisted laser cleaning with pulsed ultraviolet, visible and near-IR radiation (Invited Paper),
Grigoropoulos Costas P., University of California (USA)  [A129]
<b>Lunch</b> (12:40pm-1:20pm)
1:20pm-2:20pm: Poster Presentation
Session 9B: Laser Cleaning Workshop Training Room (6 <sup>th</sup> Floor) Chair: Arnold Nikita, Johannes Kepler Uni. Linz (Austria)
<ul> <li>Nonlinear surface waves, application to laser cleaning (Invited Paper), Mikhalevich Vladislav G., (Russia)</li> <li>Peculiarities of steam laser cleaning (Invited Paper), Veiko Vadim P., SPIFMO (Russia)</li> </ul>
Session 10B: Laser Cleaning Workshop Training Room (6 <sup>th</sup> Floor) Chair: C. P. Grigoropoulos, University of California (USA)
<ul> <li>A perspective on dry laser cleaning for semiconductor manufacturing (Invited Paper), Vereecke G, Röhr E, VanHoneymissen J.A.B, Heyns M.M, IMEC (Belgium) [A133]</li> <li>A study on parameter optimization, discoloration of pigments and yellowing effect in laser cleaning applications (Invited Paper), Zafiropulos V., Manousaki A., (Greece); Luk'yanchuk B., DSI (Singapore) [A132]</li> </ul>
Coffee Break (4:20pm-4:30pm)
Session 11B: Modification Training Room (6 <sup>th</sup> Floor) Chair: Hong MingHui, Data Storage Institute (Singapore)
<ul> <li>High resolution laser flash photography for probing the solidification of the new double laser recrystalization process, Minghong Lee, Seungjae Moon, and Costas P. Grigoropoulos, University of California, (USA); Hatano Mutsuko, Hitachi Laboratory, Hitachi Ltd., (Japan) [A004]</li> <li>Synthesis of pure C40 TiSi<sub>2</sub> for Si wafer fabrication, Chen S.Y., Shen Zexiang, NUS; See A.K., Chan L.H., Chartered Semiconductor Manufacturing Ltd., (Singapore) [A080]</li> <li>Application of photosensitive GeO<sub>2</sub>-B<sub>2</sub>O<sub>3</sub>-SiO<sub>2</sub> thin films to optical waveguide, Nishiyama Hiroaki, Miyamoto Isamu, Osaka University; Nishii Junji, Kintaka Kenji, Osaka National Research Institute (Japan) [A090]</li> <li>Domain change of liquid crystals caused by infrared laser irradiation using free electron laser system, Shimizu Yo, Mononobe Hirosato, Osaka National Research Institute, AIST-MITI; Heya Manabu, Awazu Kunio, Institute of Free Electron Laser, Graduate School of Engineering, Osaka University (Japan) [A052]</li> </ul>
<b>Break</b> (5:50pm-6:00pm)
Closing Remarks (6:00pm-6:10pm) Conference Hall (7 <sup>th</sup> Floor)  Lu YongFeng